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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

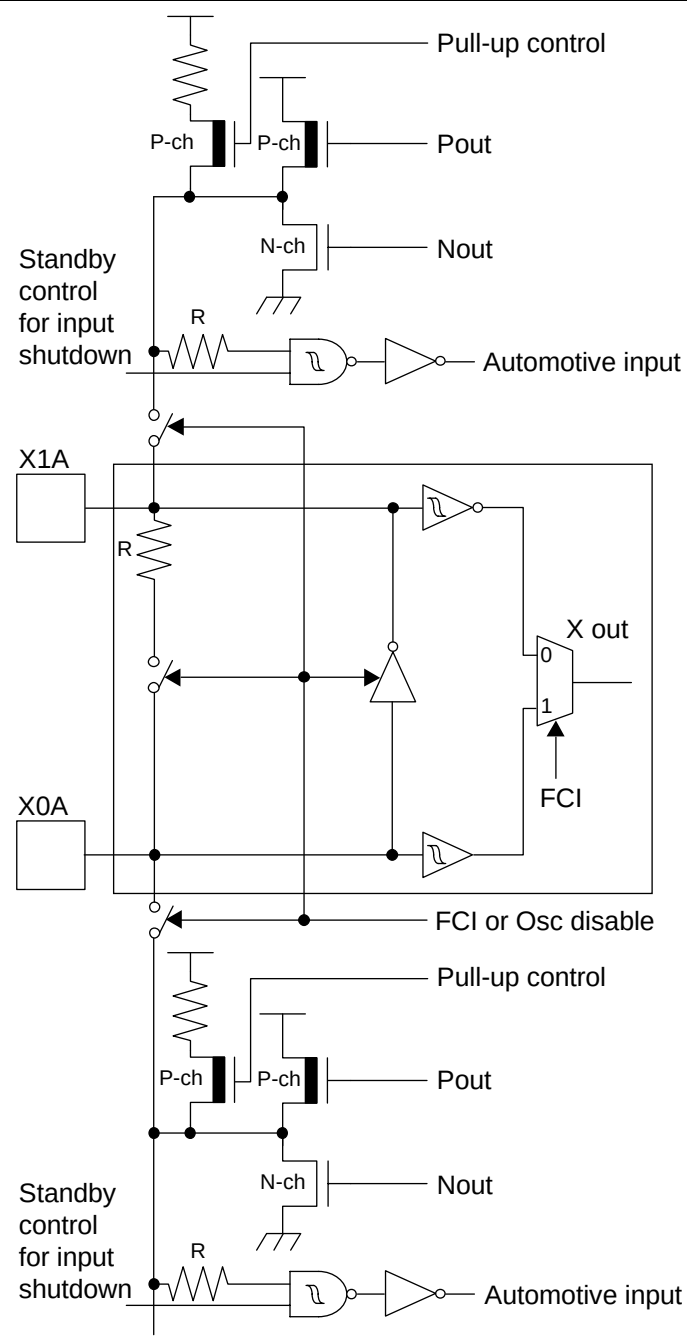
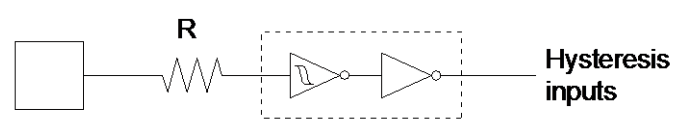
Details

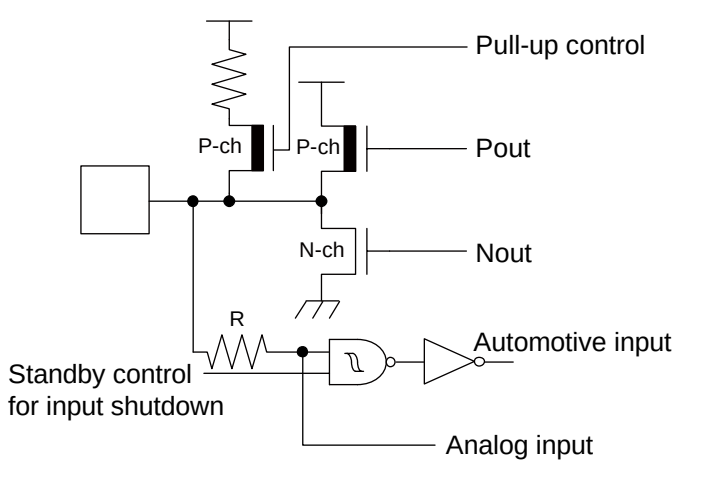
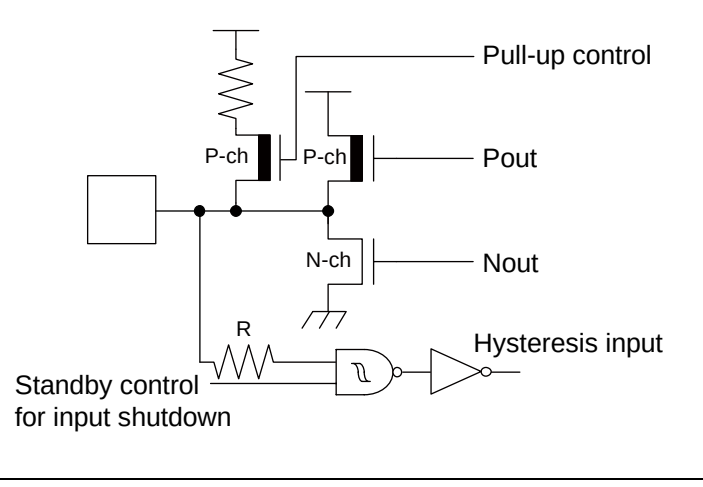
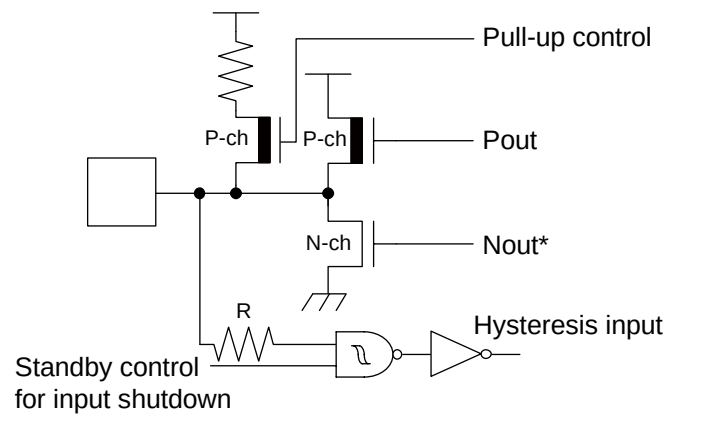
Product Status	Obsolete
Core Processor	F ² MC-16FX
Core Size	16-Bit
Speed	32MHz
Connectivity	CANbus, I ² C, LINbus, SCI, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	64
Program Memory Size	288KB (288K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 21x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb96f636rbpmc-gse1

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Type	Circuit	Remarks
B	 Pull-up control P-ch P-out N-ch N-out Standby control for input shutdown R Automotive input X1A R X0A FCI X out FCI or Osc disable Pull-up control P-ch P-out N-ch N-out Standby control for input shutdown R Automotive input	Low-speed oscillation circuit shared with GPIO functionality: • Feedback resistor = approx. 5.0MΩ • GPIO functionality selectable (CMOS level output ($I_{OL} = 4\text{mA}$, $I_{OH} = -4\text{mA}$), Automotive input with input shutdown function and programmable pull-up resistor)
C	 R Hysteresis inputs	CMOS hysteresis input pin

Type	Circuit	Remarks
K		• CMOS level output ($I_{OL} = 4\text{mA}$, $I_{OH} = -4\text{mA}$) • Automotive input with input shutdown function • Programmable pull-up resistor • Analog input
M		• CMOS level output ($I_{OL} = 4\text{mA}$, $I_{OH} = -4\text{mA}$) • CMOS hysteresis input with input shutdown function • Programmable pull-up resistor
N		• CMOS level output ($I_{OL} = 3\text{mA}$, $I_{OH} = -3\text{mA}$) • CMOS hysteresis input with input shutdown function • Programmable pull-up resistor *: N-channel transistor has slew rate control according to I²C spec, irrespective of usage.

9. User ROM Memory Map For Flash Devices

		MB96F633			MB96F635			MB96F636			MB96F637													
CPU mode address	Flash memory mode address	Flash size 64.5KB + 32KB			Flash size 128.5KB + 32KB			Flash size 256.5KB + 32KB			Flash size 384.5KB + 32KB													
FF:FFFF _H FF:0000 _H	3F:FFFF _H 3F:0000 _H	SA39 - 64KB			SA39 - 64KB			SA39 - 64KB			SA39 - 64KB		Bank A of Flash A											
FE:FFFF _H FE:0000 _H	3E:FFFF _H 3E:0000 _H	Reserved			SA38 - 64KB			SA38 - 64KB			SA38 - 64KB													
FD:FFFF _H FD:0000 _H	3D:FFFF _H 3D:0000 _H					SA37 - 64KB			SA37 - 64KB			SA37 - 64KB												
FC:FFFF _H FC:0000 _H	3C:FFFF _H 3C:0000 _H					SA36 - 64KB			SA36 - 64KB			SA36 - 64KB												
FB:FFFF _H FB:0000 _H	3B:FFFF _H 3B:0000 _H					Reserved		Reserved	SA35 - 64KB			SA35 - 64KB												
FA:FFFF _H FA:0000 _H	3A:FFFF _H 3A:0000 _H						SA34 - 64KB				SA34 - 64KB				SA34 - 64KB									
F9:FFFF _H							Reserved			Reserved	Reserved				Reserved									
DF:A000 _H		Reserved			Reserved			Reserved			Reserved		Bank B of Flash A											
DF:9FFF _H DF:8000 _H	1F:9FFF _H 1F:8000 _H													SA4 - 8KB			SA4 - 8KB			SA4 - 8KB			SA4 - 8KB	
DF:7FFF _H DF:6000 _H	1F:7FFF _H 1F:6000 _H													SA3 - 8KB			SA3 - 8KB			SA3 - 8KB			SA3 - 8KB	
DF:5FFF _H DF:4000 _H	1F:5FFF _H 1F:4000 _H													SA2 - 8KB			SA2 - 8KB			SA2 - 8KB			SA2 - 8KB	
DF:3FFF _H DF:2000 _H	1F:3FFF _H 1F:2000 _H													SA1 - 8KB			SA1 - 8KB			SA1 - 8KB			SA1 - 8KB	
DF:1FFF _H DF:0000 _H	1F:1FFF _H 1F:0000 _H													SAS - 512B*			SAS - 512B*			SAS - 512B*			SAS - 512B*	
DE:FFFF _H DE:0000 _H		Reserved			Reserved			Reserved			Reserved			Bank A of Flash A										

*: Physical address area of SAS-512B is from DF:0000_H to DF:01FF_H.

Others (from DF:0200_H to DF:1FFF_H) is mirror area of SAS-512B.

Sector SAS contains the ROM configuration block RCBA at CPU address DF:0000_H -DF:01FF_H.

SAS can not be used for E²PROM emulation.

11. Interrupt Vector Table

Vector number	Offset in vector table	Vector name	Cleared by DMA	Index in ICR to program	Description
0	3FC _H	CALLV0	No	-	CALLV instruction
1	3F8 _H	CALLV1	No	-	CALLV instruction
2	3F4 _H	CALLV2	No	-	CALLV instruction
3	3F0 _H	CALLV3	No	-	CALLV instruction
4	3EC _H	CALLV4	No	-	CALLV instruction
5	3E8 _H	CALLV5	No	-	CALLV instruction
6	3E4 _H	CALLV6	No	-	CALLV instruction
7	3E0 _H	CALLV7	No	-	CALLV instruction
8	3DC _H	RESET	No	-	Reset vector
9	3D8 _H	INT9	No	-	INT9 instruction
10	3D4 _H	EXCEPTION	No	-	Undefined instruction execution
11	3D0 _H	NMI	No	-	Non-Maskable Interrupt
12	3CC _H	DLY	No	12	Delayed Interrupt
13	3C8 _H	RC_TIMER	No	13	RC Clock Timer
14	3C4 _H	MC_TIMER	No	14	Main Clock Timer
15	3C0 _H	SC_TIMER	No	15	Sub Clock Timer
16	3BC _H	LVDI	No	16	Low Voltage Detector
17	3B8 _H	EXTINT0	Yes	17	External Interrupt 0
18	3B4 _H	EXTINT1	Yes	18	External Interrupt 1
19	3B0 _H	EXTINT2	Yes	19	External Interrupt 2
20	3AC _H	EXTINT3	Yes	20	External Interrupt 3
21	3A8 _H	EXTINT4	Yes	21	External Interrupt 4
22	3A4 _H	EXTINT5	Yes	22	External Interrupt 5
23	3A0 _H	EXTINT6	Yes	23	External Interrupt 6
24	39C _H	EXTINT7	Yes	24	External Interrupt 7
25	398 _H	EXTINT8	Yes	25	External Interrupt 8
26	394 _H	EXTINT9	Yes	26	External Interrupt 9
27	390 _H	EXTINT10	Yes	27	External Interrupt 10
28	38C _H	EXTINT11	Yes	28	External Interrupt 11
29	388 _H	EXTINT12	Yes	29	External Interrupt 12
30	384 _H	EXTINT13	Yes	30	External Interrupt 13
31	380 _H	-	-	31	Reserved
32	37C _H	EXTINT15	Yes	32	External Interrupt 15
33	378 _H	CAN0	No	33	CAN Controller 0
34	374 _H	-	-	34	Reserved
35	370 _H	-	-	35	Reserved
36	36C _H	-	-	36	Reserved
37	368 _H	-	-	37	Reserved
38	364 _H	PPG0	Yes	38	Programmable Pulse Generator 0
39	360 _H	PPG1	Yes	39	Programmable Pulse Generator 1

Vector number	Offset in vector table	Vector name	Cleared by DMA	Index in ICR to program	Description
124	20CH	-	-	124	Reserved
125	208H	-	-	125	Reserved
126	204H	-	-	126	Reserved
127	200H	-	-	127	Reserved
128	1FCH	-	-	128	Reserved
129	1F8H	-	-	129	Reserved
130	1F4H	-	-	130	Reserved
131	1F0H	-	-	131	Reserved
132	1ECH	-	-	132	Reserved
133	1E8H	FLASHA	Yes	133	Flash memory A interrupt
134	1E4H	-	-	134	Reserved
135	1E0H	-	-	135	Reserved
136	1DCH	-	-	136	Reserved
137	1D8H	QPRC0	Yes	137	Quadrature Position/Revolution counter 0
138	1D4H	QPRC1	Yes	138	Quadrature Position/Revolution counter 1
139	1D0H	ADCRC0	No	139	A/D Converter 0 - Range Comparator
140	1CCH	-	-	140	Reserved
141	1C8H	-	-	141	Reserved
142	1C4H	-	-	142	Reserved
143	1C0H	-	-	143	Reserved

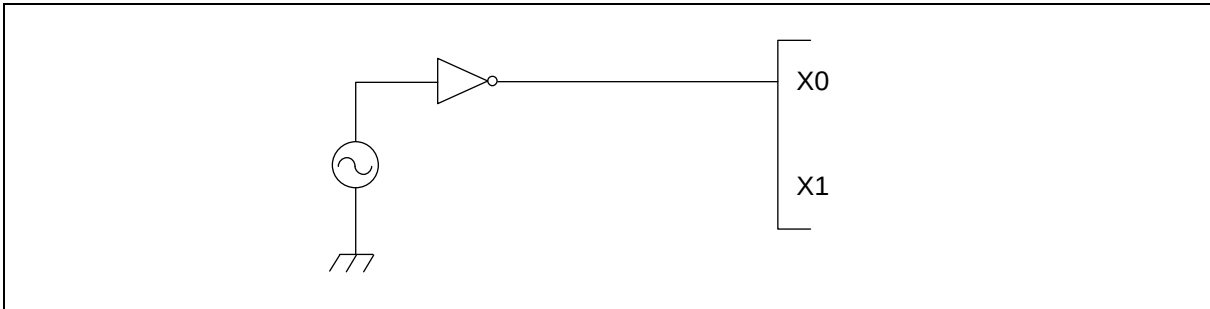
13.3 External clock usage

The permitted frequency range of an external clock depends on the oscillator type and configuration.

See AC Characteristics for detailed modes and frequency limits. Single and opposite phase external clocks must be connected as follows:

13.3.1 Single phase external clock for Main oscillator

When using a single phase external clock for the Main oscillator, X0 pin must be driven and X1 pin left open. And supply 1.8V power to the external clock.

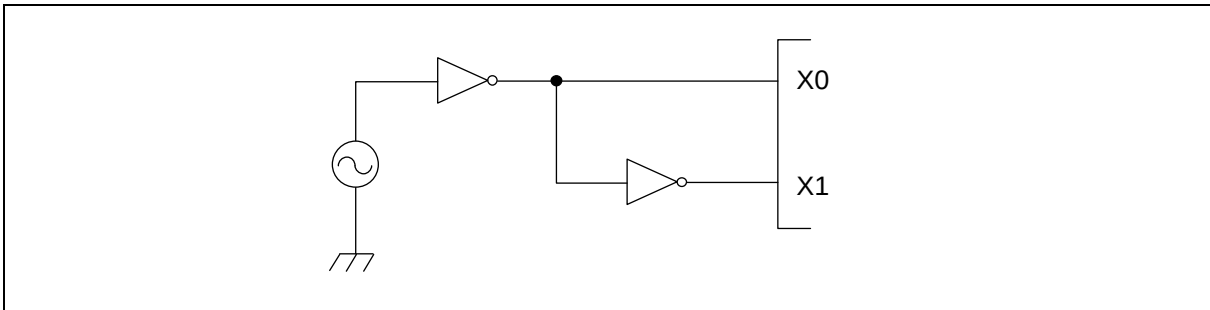


13.3.2 Single phase external clock for Sub oscillator

When using a single phase external clock for the Sub oscillator, "External clock mode" must be selected and X0A/P04_0 pin must be driven. X1A/P04_1 pin can be configured as GPIO.

13.3.3 Opposite phase external clock

When using an opposite phase external clock, X1 (X1A) pins must be supplied with a clock signal which has the opposite phase to the X0 (X0A) pins. Supply level on X0 and X1 pins must be 1.8V.



13.4 Notes on PLL clock mode operation

If the microcontroller is operated with PLL clock mode and no external oscillator is operating or no external clock is supplied, the microcontroller attempts to work with the free oscillating PLL. Performance of this operation, however, cannot be guaranteed.

13.5 Power supply pins (V_{CC}/V_{SS})

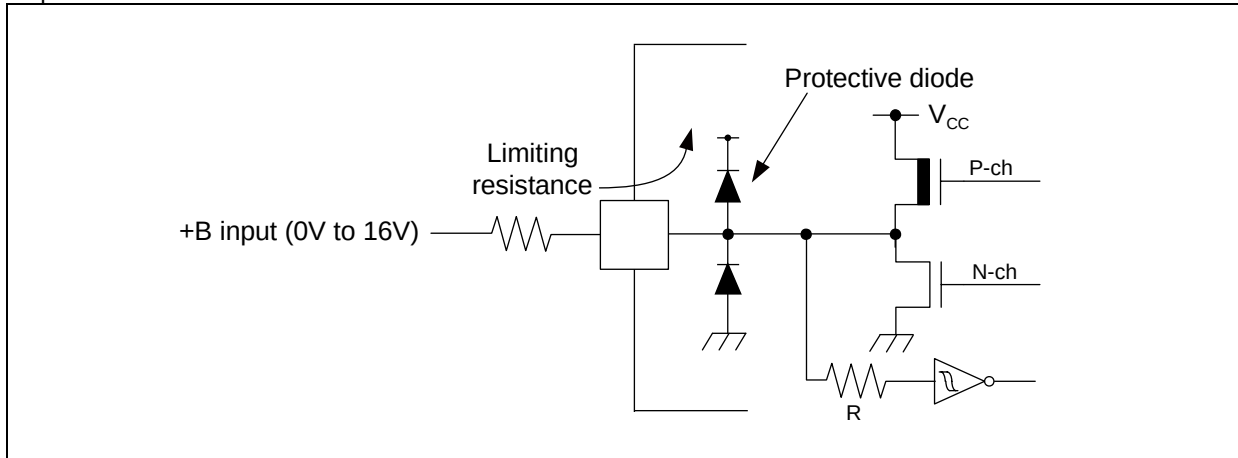
It is required that all V_{CC} -level as well as all V_{SS} -level power supply pins are at the same potential. If there is more than one V_{CC} or V_{SS} level, the device may operate incorrectly or be damaged even within the guaranteed operating range.

V_{CC} and V_{SS} pins must be connected to the device from the power supply with lowest possible impedance.

The smoothing capacitor at V_{CC} pin must use the one of a capacity value that is larger than C_s .

Besides this, as a measure against power supply noise, it is required to connect a bypass capacitor of about 0.1 μ F between V_{CC} and V_{SS} pins as close as possible to V_{CC} and V_{SS} pins.

- The DEBUG I/F pin has only a protective diode against V_{SS} . Hence it is only permitted to input a negative clamping current (4mA). For protection against positive input voltages, use an external clamping diode which limits the input voltage to maximum 6.0V.
- Sample recommended circuits:



^{*5}: The maximum permitted power dissipation depends on the ambient temperature, the air flow velocity and the thermal conductance of the package on the PCB.

The actual power dissipation depends on the customer application and can be calculated as follows:

$$P_D = P_{IO} + P_{INT}$$

$$P_{IO} = \sum (V_{OL} \times I_{OL} + V_{OH} \times I_{OH}) \text{ (I/O load power dissipation, sum is performed on all I/O ports)}$$

$$P_{INT} = V_{CC} \times (I_{CC} + I_A) \text{ (internal power dissipation)}$$

I_{CC} is the total core current consumption into V_{CC} as described in the "DC characteristics" and depends on the selected operation mode and clock frequency and the usage of functions like Flash programming.

I_A is the analog current consumption into AV_{CC} .

^{*6}: Worst case value for a package mounted on single layer PCB at specified T_A without air flow.

^{*7}: Write/erase to a large sector in flash memory is warranted with $T_A \leq +105^\circ\text{C}$.

WARNING

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

14.3 DC Characteristics

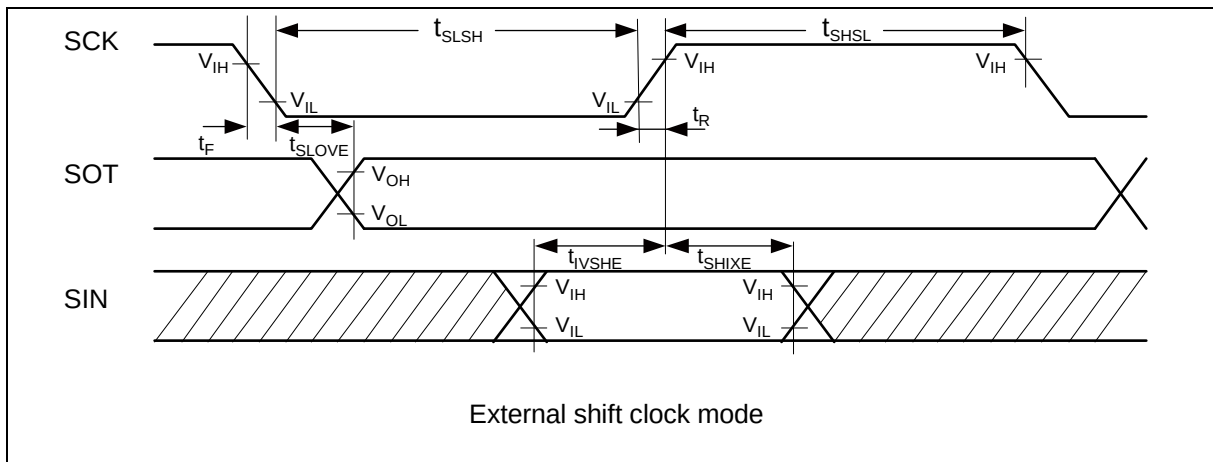
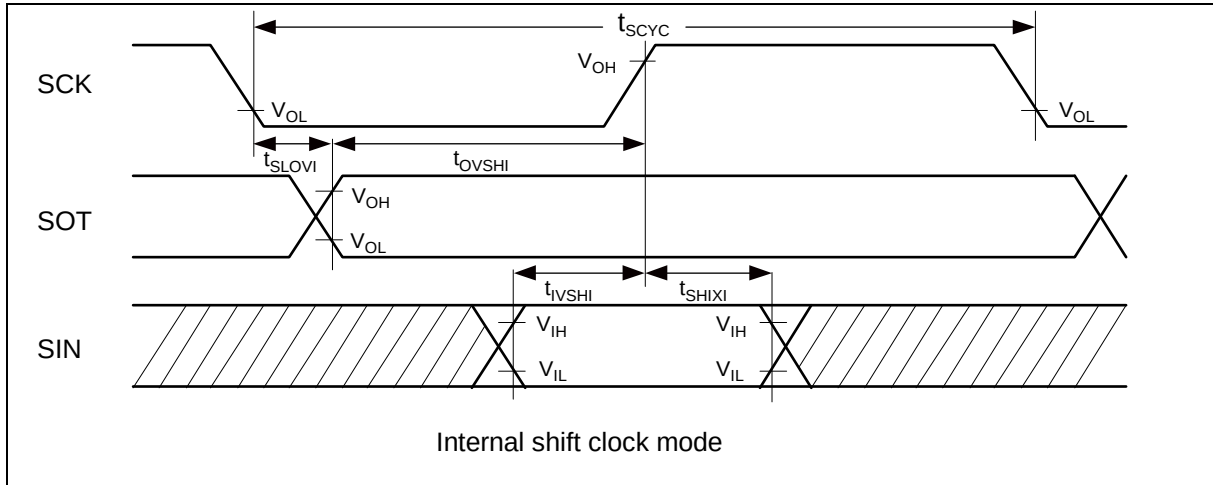
14.3.1 Current Rating

($V_{CC} = AV_{CC} = 2.7V$ to $5.5V$, $V_{SS} = AV_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+125^{\circ}C$)

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Power supply current in Run modes*1	I _{CCPLL}	V _{CC}	PLL Run mode with CLKS1/2 = CLKB = CLKP1/2 = 32MHz	-	27	-	mA	T _A = +25°C
			Flash 0 wait	-	-	37	mA	T _A = +105°C
			(CLKRC and CLKSC stopped)	-	-	38.5	mA	T _A = +125°C
	I _{CCMAIN}		Main Run mode with CLKS1/2 = CLKB = CLKP1/2 = 4MHz	-	3.5	-	mA	T _A = +25°C
			Flash 0 wait	-	-	8	mA	T _A = +105°C
			(CLKPLL, CLKSC and CLKRC stopped)	-	-	9.5	mA	T _A = +125°C
	I _{CCRCH}		RC Run mode with CLKS1/2 = CLKB = CLKP1/2 = CLKRC = 2MHz	-	1.8	-	mA	T _A = +25°C
			Flash 0 wait	-	-	6	mA	T _A = +105°C
			(CLKMC, CLKPLL and CLKSC stopped)	-	-	7.5	mA	T _A = +125°C
	I _{CCRCL}		RC Run mode with CLKS1/2 = CLKB = CLKP1/2 = CLKRC = 100kHz	-	0.16	-	mA	T _A = +25°C
			Flash 0 wait	-	-	3.5	mA	T _A = +105°C
			(CLKMC, CLKPLL and CLKSC stopped)	-	-	5	mA	T _A = +125°C
	I _{CCSUB}		Sub Run mode with CLKS1/2 = CLKB = CLKP1/2 = 32kHz	-	0.1	-	mA	T _A = +25°C
			Flash 0 wait	-	-	3.3	mA	T _A = +105°C
			(CLKMC, CLKPLL and CLKRC stopped)	-	-	4.8	mA	T _A = +125°C

14.3.2 Pin Characteristics
 $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = 0V, T_A = -40^{\circ}C \text{ to } +125^{\circ}C)$

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
"H" level input voltage	V_{IH}	Port inputs Pnn_m	-	$V_{CC} \times 0.7$	-	$V_{CC} + 0.3$	V	CMOS Hysteresis input
			-	$V_{CC} \times 0.8$	-	$V_{CC} + 0.3$	V	AUTOMOTIVE Hysteresis input
	V_{IHX0S}	X0	External clock in "Fast Clock Input mode"	$V_D \times 0.8$	-	V_D	V	$V_D = 1.8V \pm 0.15V$
	V_{IHX0AS}	X0A	External clock in "Oscillation mode"	$V_{CC} \times 0.8$	-	$V_{CC} + 0.3$	V	
	V_{IHR}	RSTX	-	$V_{CC} \times 0.8$	-	$V_{CC} + 0.3$	V	CMOS Hysteresis input
	V_{IHM}	MD	-	$V_{CC} - 0.3$	-	$V_{CC} + 0.3$	V	CMOS Hysteresis input
	V_{IHD}	DEBUG I/F	-	2.0	-	$V_{CC} + 0.3$	V	TTL Input
"L" level input voltage	V_{IL}	Port inputs Pnn_m	-	$V_{SS} - 0.3$	-	$V_{CC} \times 0.3$	V	CMOS Hysteresis input
			-	$V_{SS} - 0.3$	-	$V_{CC} \times 0.5$	V	AUTOMOTIVE Hysteresis input
	V_{ILX0S}	X0	External clock in "Fast Clock Input mode"	V_{SS}	-	$V_D \times 0.2$	V	$V_D = 1.8V \pm 0.15V$
	V_{ILX0AS}	X0A	External clock in "Oscillation mode"	$V_{SS} - 0.3$	-	$V_{CC} \times 0.2$	V	
	V_{ILR}	RSTX	-	$V_{SS} - 0.3$	-	$V_{CC} \times 0.2$	V	CMOS Hysteresis input
	V_{ILM}	MD	-	$V_{SS} - 0.3$	-	$V_{SS} + 0.3$	V	CMOS Hysteresis input
	V_{ILD}	DEBUG I/F	-	$V_{SS} - 0.3$	-	0.8	V	TTL Input
"H" level output voltage	V_{OH4}	4mA type	$4.5V \leq V_{CC} \leq 5.5V$ $I_{OH} = -4mA$	$V_{CC} - 0.5$	-	V_{CC}	V	
			$2.7V \leq V_{CC} < 4.5V$ $I_{OH} = -1.5mA$					
	V_{OH3}	3mA type	$4.5V \leq V_{CC} \leq 5.5V$ $I_{OH} = -3mA$	$V_{CC} - 0.5$	-	V_{CC}	V	
			$2.7V \leq V_{CC} < 4.5V$ $I_{OH} = -1.5mA$					
"L" level output voltage	V_{OL4}	4mA type	$4.5V \leq V_{CC} \leq 5.5V$ $I_{OL} = +4mA$	-	-	0.4	V	
			$2.7V \leq V_{CC} < 4.5V$ $I_{OL} = +1.7mA$					
	V_{OL3}	3mA type	$2.7V \leq V_{CC} < 5.5V$ $I_{OL} = +3mA$	-	-	0.4	V	
			$V_{CC} = 2.7V$ $I_{OL} = +25mA$					
	V_{OLD}	DEBUG I/F		0	-	0.25	V	



14.5 A/D Converter

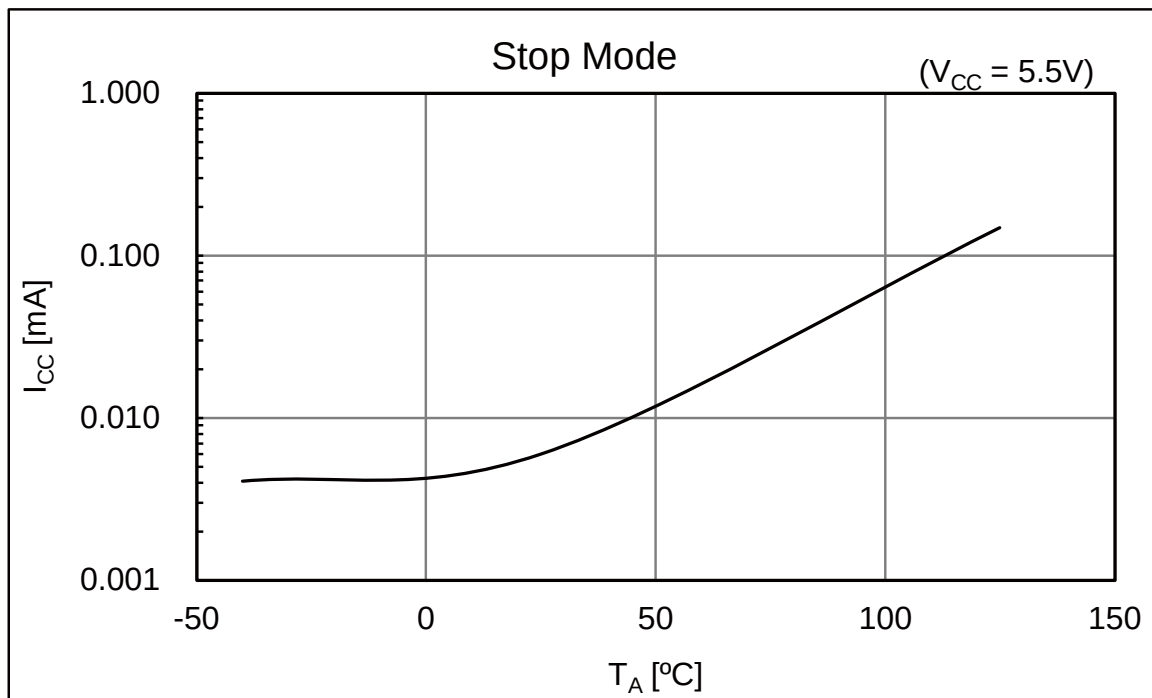
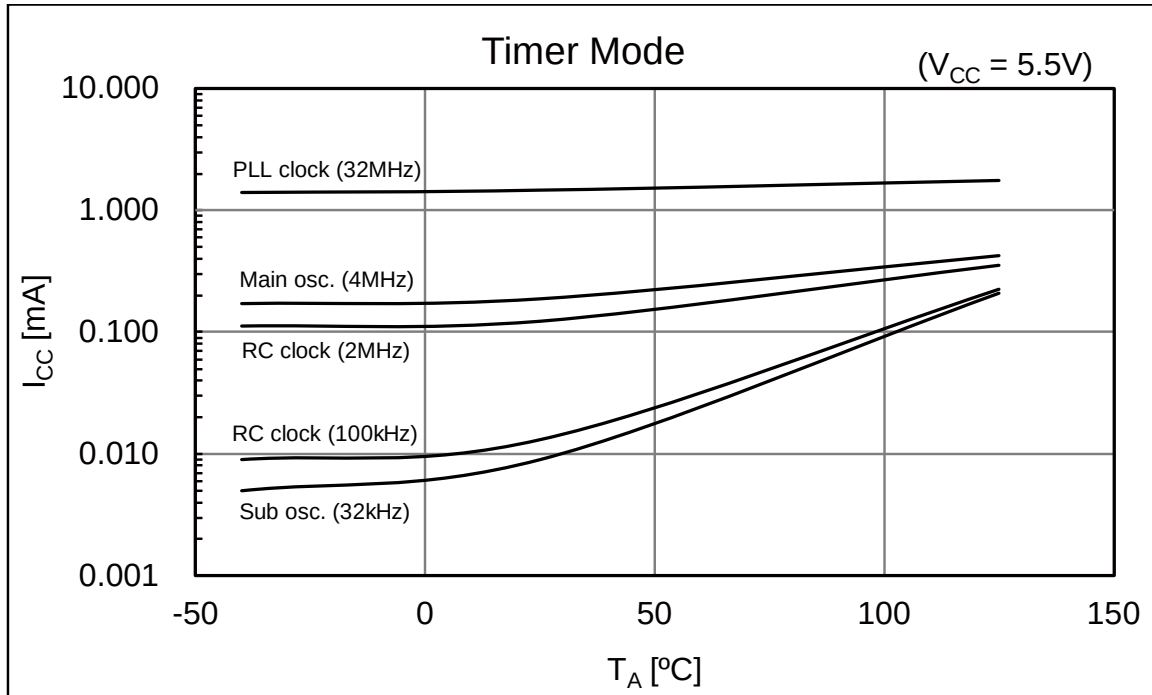
14.5.1 Electrical Characteristics for the A/D Converter

($V_{CC} = AV_{CC} = 2.7V$ to $5.5V$, $V_{SS} = AV_{SS} = 0V$, $T_A = -40^{\circ}C$ to $+125^{\circ}C$)

Parameter	Symbol	Pin name	Value			Unit	Remarks
			Min	Typ	Max		
Resolution	-	-	-	-	10	bit	
Total error	-	-	- 3.0	-	+ 3.0	LSB	
Nonlinearity error	-	-	- 2.5	-	+ 2.5	LSB	
Differential Nonlinearity error	-	-	- 1.9	-	+ 1.9	LSB	
Zero transition voltage	V_{OT}	ANn	Typ - 20	$AV_{SS} + 0.5LSB$	Typ + 20	mV	
Full scale transition voltage	V_{FST}	ANn	Typ - 20	$AV_{RH} - 1.5LSB$	Typ + 20	mV	
Compare time*	-	-	1.0	-	5.0	μs	$4.5V \leq AV_{CC} \leq 5.5V$
			2.2	-	8.0	μs	$2.7V \leq AV_{CC} < 4.5V$
Sampling time*	-	-	0.5	-	-	μs	$4.5V \leq AV_{CC} \leq 5.5V$
			1.2	-	-	μs	$2.7V \leq AV_{CC} < 4.5V$
Power supply current	I_A	AV_{CC}	-	2.0	3.1	mA	A/D Converter active
	I_{AH}		-	-	3.3	μA	A/D Converter not operated
Reference power supply current (between AV_{RH} and AV_{SS})	I_R	AV_{RH}	-	520	810	μA	A/D Converter active
	I_{RH}		-	-	1.0	μA	A/D Converter not operated
Analog input capacity	C_{VIN}	ANn	-	-	15.9	pF	
Analog impedance	R_{VIN}	ANn	-	-	2050	Ω	$4.5V \leq AV_{CC} \leq 5.5V$
			-	-	3600	Ω	$2.7V \leq AV_{CC} < 4.5V$
Analog port input current (during conversion)	I_{AIN}	ANn	- 0.3	-	+ 0.3	μA	$AV_{SS} < V_{AIN} < AV_{CC}, AV_{RH}$
Analog input voltage	V_{AIN}	ANn	AV_{SS}	-	AV_{RH}	V	
Reference voltage range	-	AV_{RH}	$AV_{CC} - 0.1$	-	AV_{CC}	V	
Variation between channels	-	ANn	-	-	4.0	LSB	

*: Time for each channel.

■ MB96F637



■ Used setting

Mode	Selected Source Clock	Clock/Regulator and FLASH Settings
Run mode	PLL	CLKS1 = CLKS2 = CLKB = CLKP1 = CLKP2 = 32MHz
	Main osc.	CLKS1 = CLKS2 = CLKB = CLKP1 = CLKP2 = 4MHz
	RC clock fast	CLKS1 = CLKS2 = CLKB = CLKP1 = CLKP2 = 2MHz
	RC clock slow	CLKS1 = CLKS2 = CLKB = CLKP1 = CLKP2 = 100kHz
	Sub osc.	CLKS1 = CLKS2 = CLKB = CLKP1 = CLKP2 = 32kHz
Sleep mode	PLL	CLKS1 = CLKS2 = CLKP1 = CLKP2 = 32MHz Regulator in High Power Mode, (CLKB is stopped in this mode)
	Main osc.	CLKS1 = CLKS2 = CLKP1 = CLKP2 = 4MHz Regulator in High Power Mode, (CLKB is stopped in this mode)
	RC clock fast	CLKS1 = CLKS2 = CLKP1 = CLKP2 = 2MHz Regulator in High Power Mode, (CLKB is stopped in this mode)
	RC clock slow	CLKS1 = CLKS2 = CLKP1 = CLKP2 = 100kHz Regulator in Low Power Mode, (CLKB is stopped in this mode)
	Sub osc.	CLKS1 = CLKS2 = CLKP1 = CLKP2 = 32kHz Regulator in Low Power Mode, (CLKB is stopped in this mode)
Timer mode	PLL	CLKMC = 4MHz, CLKPLL = 32MHz (System clocks are stopped in this mode) Regulator in High Power Mode, FLASH in Power-down / reset mode
	Main osc.	CLKMC = 4MHz (System clocks are stopped in this mode) Regulator in High Power Mode, FLASH in Power-down / reset mode
	RC clock fast	CLKMC = 2MHz (System clocks are stopped in this mode) Regulator in High Power Mode, FLASH in Power-down / reset mode
	RC clock slow	CLKMC = 100kHz (System clocks are stopped in this mode) Regulator in Low Power Mode, FLASH in Power-down / reset mode
	Sub osc.	CLKMC = 32 kHz (System clocks are stopped in this mode) Regulator in Low Power Mode, FLASH in Power-down / reset mode
Stop mode	stopped	(All clocks are stopped in this mode) Regulator in Low Power Mode, FLASH in Power-down / reset mode

16. Ordering Information

MCU with CAN controller

Part number	Flash memory	Package*
MB96F633RBPMC-GSE1	Flash A (96.5KB)	80-pin plastic LQFP (FPT-80P-M21)
MB96F633RBPMC-GSE2		
MB96F635RBPMC-GSE1	Flash A (160.5KB)	80-pin plastic LQFP (FPT-80P-M21)
MB96F635RBPMC-GSE2		
MB96F636RBPMC-GSE1	Flash A (288.5KB)	80-pin plastic LQFP (FPT-80P-M21)
MB96F636RBPMC-GSE2		
MB96F637RBPMC-GSE1	Flash A (416.5KB)	80-pin plastic LQFP (FPT-80P-M21)
MB96F637RBPMC-GSE2		

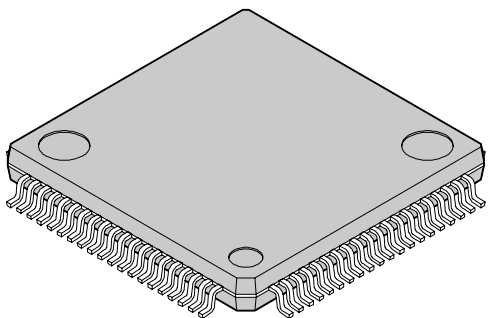
*: For details about package, see "Package Dimension".

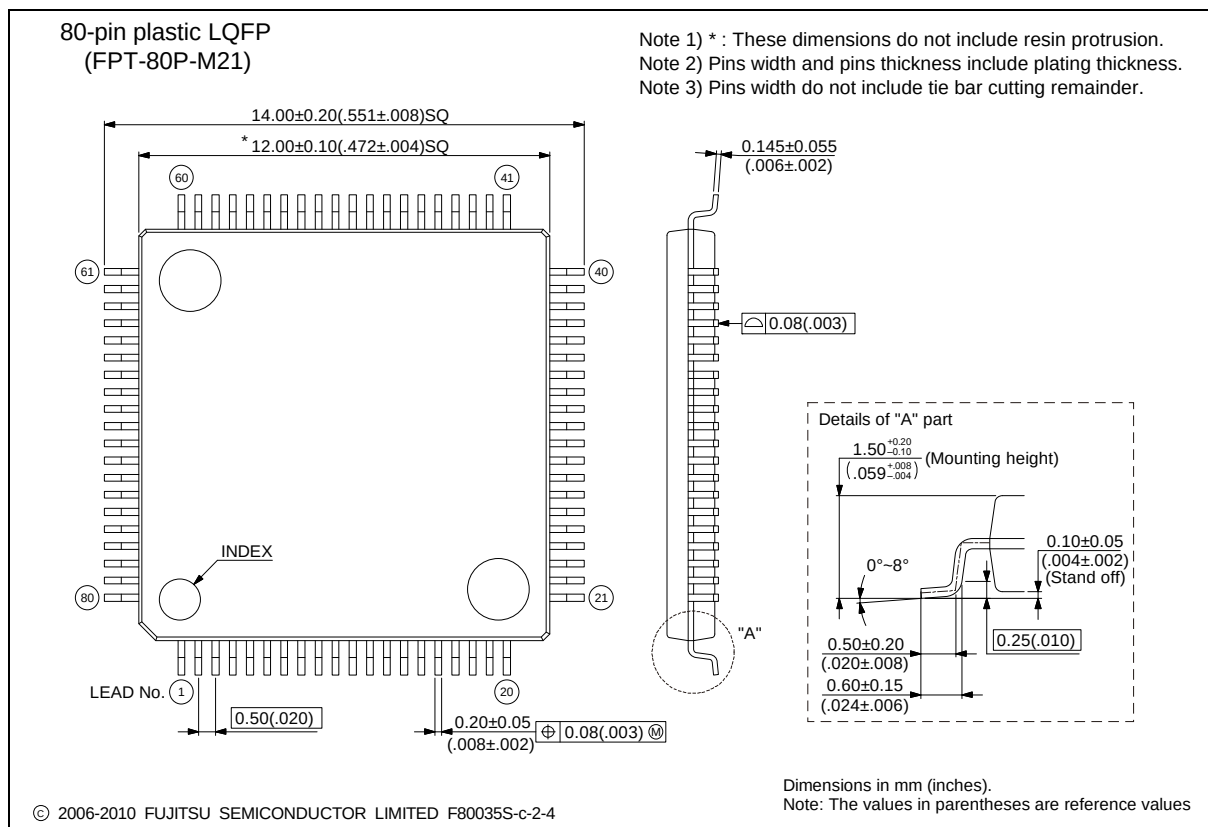
MCU without CAN controller

Part number	Flash memory	Package*
MB96F633ABPMC-GSE1	Flash A (96.5KB)	80-pin plastic LQFP (FPT-80P-M21)
MB96F633ABPMC-GSE2		
MB96F635ABPMC-GSE1	Flash A (160.5KB)	80-pin plastic LQFP (FPT-80P-M21)
MB96F635ABPMC-GSE2		

*: For details about package, see "Package Dimension".

17. Package Dimension

 80-pin plastic LQFP (FPT-80P-M21)	Lead pitch	0.50 mm
	Package width × package length	12 mm × 12 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.70 mm Max
	Weight	0.47 g
	Code (Reference)	P-LFQFP80-12×12-0.50



Page	Section	Change Results
21	Interrupt Vector Table	Changed the Description of CALLV0 to CALLV7 Reserved → CALLV instruction
		Changed the Description of RESET Reserved → Reset vector
		Changed the Description of INT9 Reserved → INT9 instruction
		Changed the Description of EXCEPTION Reserved → Undefined instruction execution
22		Changed the Vector name of Vector number 64 PPGRLT → RLT6
		Changed the Description of Vector number 64 Reload Timer 6 can be used as PPG clock source → Reload Timer 6
25 to 28	Handling Precautions	Added a section
30	Handling Devices	Added the description to "3. External clock usage" (3) Opposite phase external clock
		Changed the description in "7. Turn on sequence of power supply to A/D converter and analog inputs" In this case, the voltage must not exceed AVR _H or AV _{CC} → In this case, AVR _H must not exceed AV _{CC} . Input voltage for ports shared with analog input ports also must not exceed AV _{CC}
31		Added the description "12. Mode Pin (MD)"
33	Electrical Characteristics 1. Absolute Maximum Ratings	Changed the annotation *4 Note that if the +B input is applied during power-on, the power supply is provided from the pins and the resulting supply voltage may not be sufficient to operate the Power reset (except devices with persistent low voltage reset in internal vector mode). → Note that if the +B input is applied during power-on, the power supply is provided from the pins and the resulting supply voltage may not be sufficient to operate the Power reset.
33	1. Absolute Maximum Ratings	Added the annotation *4 The DEBUG I/F pin has only a protective diode against V _{SS} . Hence it is only permitted to input a negative clamping current (4mA). For protection against positive input voltages, use an external clamping diode which limits the input voltage to maximum 6.0V.
35	2. Recommended Operating Conditions	Added the Value and Remarks to "Power supply voltage" Min: 2.0V Typ: - Max: 5.5V Remarks: Maintains RAM data in stop mode
		Changed the Value of "Smoothing capacitor at C pin" Typ: 1.0μF → 1.0μF to 3.9μF Max: 1.5μF → 4.7μF
		Changed the Remarks of "Smoothing capacitor at C pin" Deleted "(Target value)" Added "3.9μF (Allowance within ± 20%)"

Page	Section	Change Results
57	7. Flash Memory Write/Erase Characteristics	Changed the Value of "Sector erase time"
		Added "Security Sector" to "Sector erase time"
		Changed the Parameter "Half word (16 bit) write time" → "Word (16-bit) write time"
		Changed the Value of "Chip erase time"
		Changed the Remarks of "Sector erase time" Excludes write time prior to internal erase → Includes write time prior to internal erase
		Added the Note and annotation *1
		Deleted "(targeted value)" from title " Write/Erase cycles and data hold time"
58 to 60	Example Characteristics	Added a section
61	Ordering Information	Changed part number MCU with CAN controller MB96F636RAPMC-GSE1* → MB96F636RBPMC-GSE1 MB96F636RAPMC-GSE2* → MB96F636RBPMC-GSE2 MB96F637RAPMC-GSE1* → MB96F637RBPMC-GSE1 MB96F637RAPMC-GSE2* → MB96F637RBPMC-GSE2
61	Ordering Information	Added part number MCU with CAN controller MB96F633RBPMC-GSE1 MB96F633RBPMC-GSE2 MB96F635RBPMC-GSE1 MB96F635RBPMC-GSE2 MCU without CAN controller MB96F633ABPMC-GSE1 MB96F633ABPMC-GSE2 MB96F635ABPMC-GSE1 MB96F635ABPMC-GSE2
Revision 1.1		
-	-	Company name and layout design change

NOTE: Please see "Document History" about later revised information.

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